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APPLICANT : SONY CORP;

INVENTOR : ITOU MUTSUSADA;

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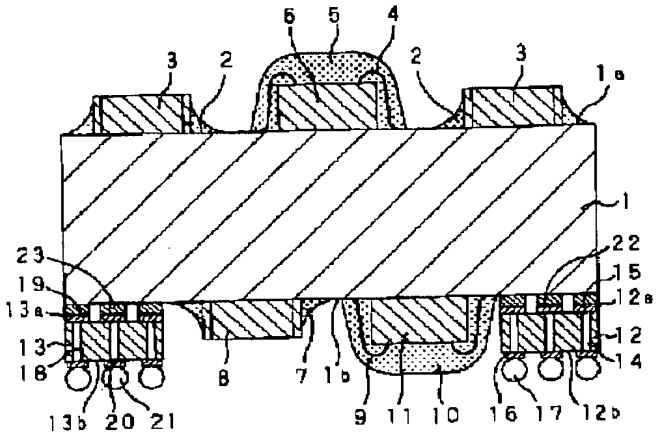
TITLE : ELECTRONIC PART AND ITS MANUFACTURE



ABSTRACT : PROBLEM TO BE SOLVED: To enable mounting of a chip part on a solder ball formation side for improving its mounting density.

SOLUTION: Chip parts 3, 6, 8 and 11 are mounted on opposing major surfaces 1a and 1b of a substrate 1 respectively, and spacers 12 and 13 which are higher in level than the mounted chip parts 8 and 11 are mounted also on the major surface 1b. The spacers 12 and 13 are arranged so that one major surfaces 12a and 13a of the spacers facing the substrate are conducted with major surfaces 12b and 13b thereof opposed thereto, solder balls 17 and 21 are placed on the spacers 12 and 13 to be connected with the chip parts 3, 6, 8, and 11 through the spacer 12 and 13, and function as terminals for interconnection with the external devices.

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(71)Applicant : **SONY CORP**
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ITOU MUTSUSADA

(54) ELECTRONIC PART AND ITS MANUFACTURE

(57)Abstract:
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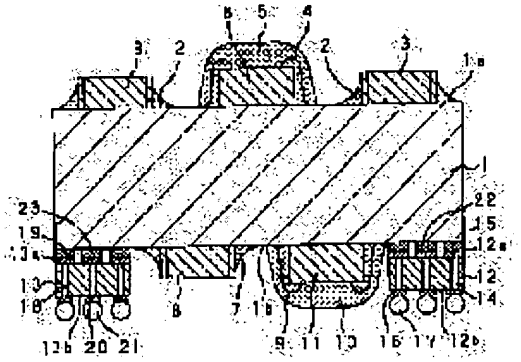

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